APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention

Micromachined Capacitive RF Pressure Sensor

Application Type: regular, utility

Request Not To Publish

I/We hereby request that the attached application not be published under 37 U.S.C. 122(b).

I/We hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Publication Information:

Suggested Figure for Publication - 7

Suggested Classification - 73/718

Suggested Technology Center -

Total Number of Drawing Sheets - 11

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